

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
 For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	30	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _{RM}		
DC Forward Current	I _F (Per diode)	0.3	A
Average Rectified Output Current	I _O		
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	1	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance	R _{θJA}	261	°C/W
Thermal Resistance Junction to Ambient (Note 5)			
Typical Thermal Resistance	R _{θJA}	445	°C/W
Thermal Resistance Junction to Ambient (Note 6)			
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop	V _F	—	—	240	mV	I _F = 0.1mA, T _J = +25°C
		—	—	300		I _F = 1mA, T _J = +25°C
		—	—	375		I _F = 10mA, T _J = +25°C
		—	—	430		I _F = 30mA, T _J = +25°C
		—	—	500		I _F = 100mA, T _J = +25°C
		—	—	580		I _F = 200mA, T _J = +25°C
		—	530	—		I _F = 300mA, T _J = +25°C
Leakage Current (Note 7)	I _R	—	—	5	μA	V _R = 30V, T _J = +25°C
		—	0.63	3		V _R = 25V, T _J = +25°C
		—	—	1		V _R = 10V, T _J = +25°C
		—	0.35	0.8		V _R = 5V, T _J = +25°C
		—	7	20		V _R = 10V, T _J = +70°C
		—	18	50		V _R = 10V, T _J = +85°C

Notes: 5. Device mounted on Polyimide substrate, 10cm x 10cm, 2oz, copper, PC boards.
 6. Device mounted on FR-4 PCB, 2oz. Copper, minimum recommended pad layout per <http://www.diodes.com/datasheets/ap02001.pdf>.
 7. Short duration pulse test used to minimize self-heating effect.

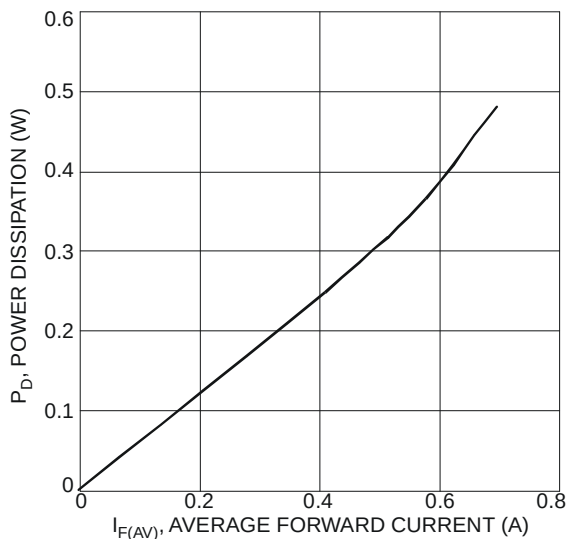


Figure 1. Forward Power Dissipation

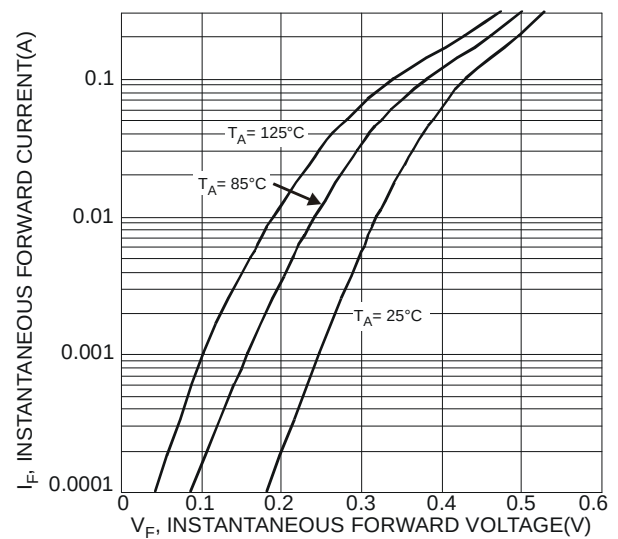
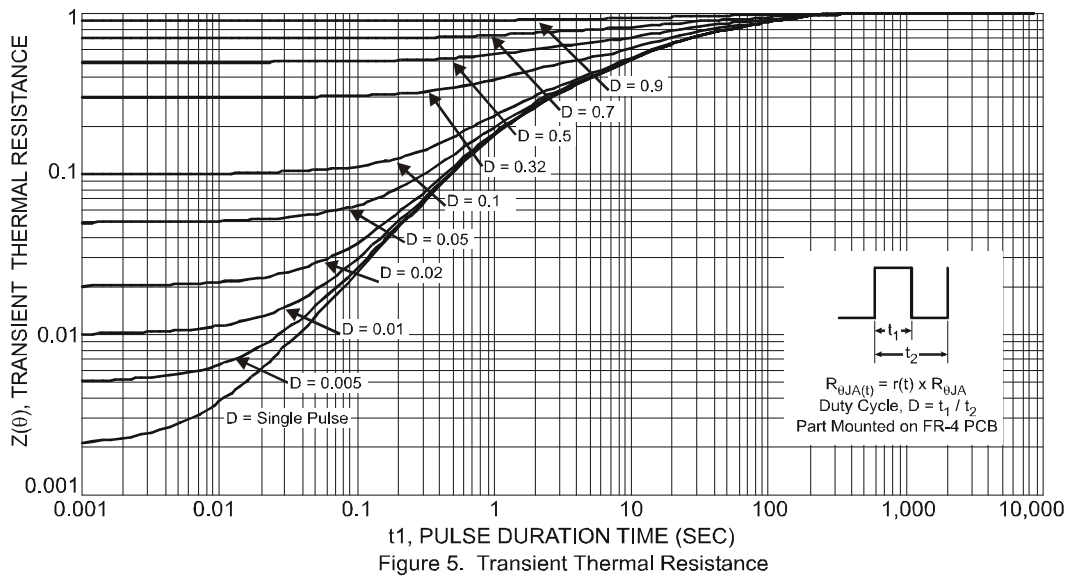
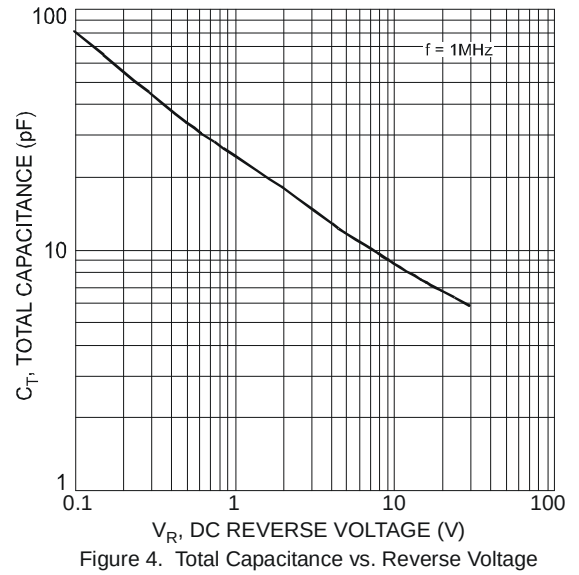
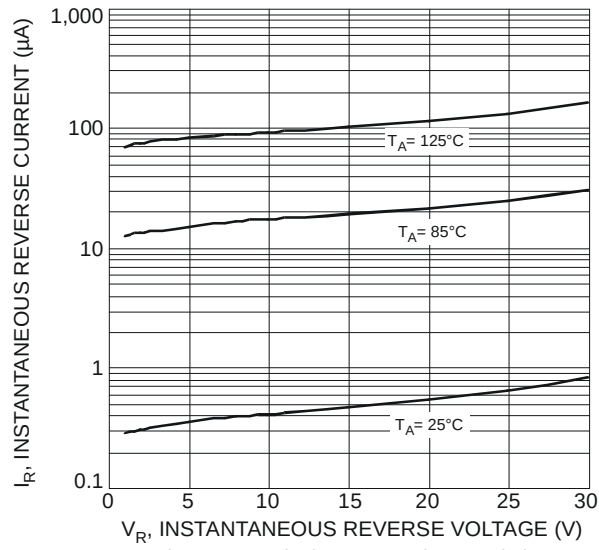
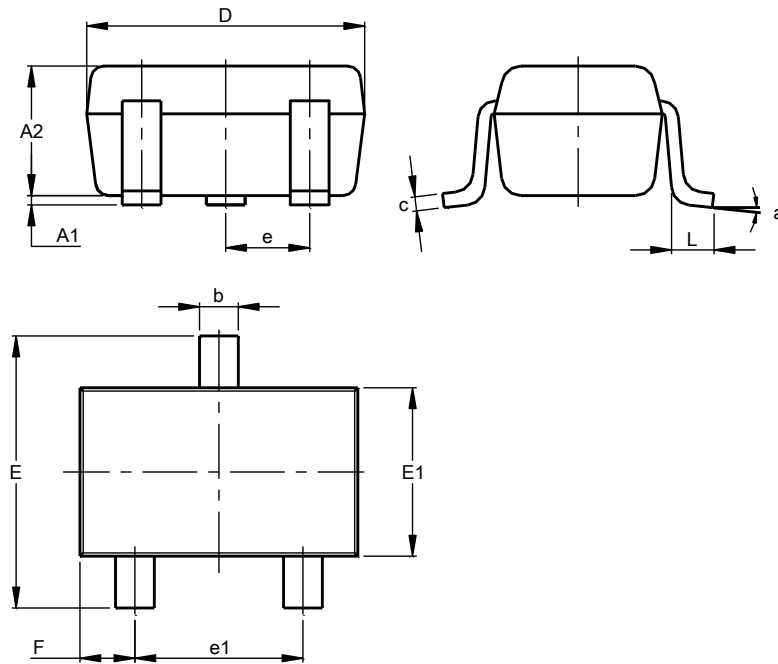


Figure 2. Typical Forward Characteristics



Package Outline Dimensions

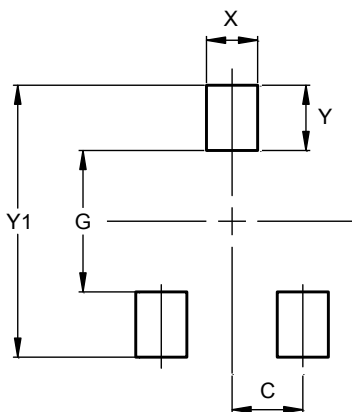
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SOT323			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.90	1.00	0.95
b	0.25	0.40	0.30
c	0.10	0.18	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
e1	1.20	1.40	1.30
F	0.375	0.475	0.425
L	0.25	0.40	0.30
a	8°		
All Dimensions in mm			

Suggested Pad Layout

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.650
G	1.300
X	0.470
Y	0.600
Y1	2.500

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